

METHOD AND APPARATUS FOR A LASER SYSTEM FOR SEVERING SEMICONDUCTOR WAFERS

ABSTRACT

5

A laser system 100 comprises a laser handler 115 for providing laser beam(s) 135 and 160 from one or more laser sources 120 and 125, an optical system handler 135 for manipulating the laser beam(s) 135 and 160 and providing manipulated laser beam(s) 165 directed at scribing lanes on a semiconductor wafer 145. The laser beam(s) 165 for evaporating portion of the semiconductor wafer 145 in the scribing lanes by ablative photodecomposition. An image recognition system 170 provides feedback to a controller 130 that controls the operation of the system 100.

10
15

FIG. 1 accompanies the abstract.